NICHIA CORPORATION

SPECIFICATIONS FOR WHITE LED

PART NO. NVSW219CT-V2

- Pb-free Reflow Soldering Application
- ESD Withstand Voltage (HBM) Class 3B
- RoHS Compliant



SPECIFICATIONS

(1) Absolute Maximum Ratings

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	${ m I}_{\sf F}$	1800	mA
Pulse Forward Current	${ m I}_{\sf FP}$	2400	mA
ESD Withstand Voltage (HBM)	V_{ESD}	8	kV
Allowable Reverse Current	${ m I}_{ m R}$	85	mA
Power Dissipation	P _D	5.58	W
Operating Temperature	Topr	-40~100	°C
Storage Temperature	T _{stg}	-40~100	°C
Junction Temperature	Tı	150	°C

- * Absolute Maximum Ratings at $T_1=25$ °C.
- * I_{FP} conditions with pulse width $\leq\!10\text{ms}$ and duty cycle $\leq\!10\%.$
- * For I_{F} and $I_{\text{FP}}\text{,}$ see the "DERATING CHARACTERISTICS" of this specification.
- * HBM ESD Component Classification Level of the LEDs: Class 3B For more details, see ANSI/ESDA/JEDEC JS-001.

(2) Initial Electrical/Optical Characteristics

2) Initial Electrical/Optic	al Characteristics				T	
	[tem	Symbol	Condition	Тур	Max	Unit
Forward Voltage		V _F	I _F =700mA	2.89	-	V
	Luminous Flux (Chromaticity Coordinate1)	Фу	I _F =700mA	335	-	lm
R70	Luminous Intensity (Chromaticity Coordinate1)	Iv	I _F =700mA	114	-	cd
	Color Rendering Index (Chromaticity Coordinate1)	Ra	I _F =700mA	72	-	-
	x		I _F =700mA	0.3818	-	
Chromaticity Coordinate1	у	-	I _F =700mA	0.3797	-	-
R8000	Luminous Flux (Chromaticity Coordinate2)	Фи	I _F =700mA	285	-	lm
	Luminous Intensity (Chromaticity Coordinate2)	I _v	I _F =700mA	97	-	cd
	Color Rendering Index (Chromaticity Coordinate2)	R _a	I _F =700mA	83	-	-
	Luminous Flux (Chromaticity Coordinate2)	Фи	I _F =700mA	242	-	lm
R9050	Luminous Intensity (Chromaticity Coordinate2)	I _v	I _F =700mA	84	-	cd
	Color Rendering Index (Chromaticity Coordinate2)	Ra	I _F =700mA	93	-	-
	х		I _F =700mA	0.4338	-	
Chromaticity Coordinate2	у	-	I _F =700mA	0.4030	-	-

I	tem	Symbol	Condition	Тур	Max	Unit
	Luminous Flux (Chromaticity Coordinate3)	Ф٧	I _F =700mA	340	-	lm
R70	Luminous Intensity (Chromaticity Coordinate3)	Iv	I _F =700mA	114	-	cd
	Color Rendering Index (Chromaticity Coordinate3)	Ra	I _F =700mA	72	-	-
	Luminous Flux (Chromaticity Coordinate3)	Фу	I _F =700mA	305	-	lm
R8000	Luminous Intensity (Chromaticity Coordinate3)	Ι _ν	I _F =700mA	104	-	cd
	Color Rendering Index (Chromaticity Coordinate3)	Ra	I _F =700mA	83	-	-
	Luminous Flux (Chromaticity Coordinate3)	Фи	I _F =700mA	262	-	lm
R9050	Luminous Intensity (Chromaticity Coordinate3)	Ι _ν	I _F =700mA	90	-	cd
	Color Rendering Index (Chromaticity Coordinate3)	Ra	I _F =700mA	93	-	-
Characticity Consider 1 2	Х		I _F =700mA	0.3447	-	
Chromaticity Coordinate3	у	-	I _F =700mA	0.3553	-	-
Thermal Resistance		Rejs	=	2.5	4.2	°C/W

^{*} Characteristics at T_1 =25°C and measured in pulse mode.

 $^{^{}st}$ Optical Characteristics as per CIE 127:2007 standard.

^{*} Chromaticity Coordinates as per CIE 1931 Chromaticity Chart.

^{*} $R_{\theta JS}$ is the thermal resistance from the junction to the T_S measurement point.

^{*} $R_{\theta JS}$ is measured using the Dynamic Mode detailed in JESD51-1.

^{*} The Max value for the $R_{\mbox{\scriptsize 0JS}}$ is for reference purposes only.

RANKS

Item	Rank		Condition	Min	Max	Unit	
Forward Voltage	-		I _F =700mA	2.7	3.1	V	
	T295f15			295	370		
	T280f14			280	350		
	T270f13			270	335		
	T250f13			250	315		
Luminous Flux	T230f12		I _F =700mA	230	290	lm	
	T225f11			225	280		
	T220f11			220	275		
	T215f11			215	270		
	T200f11			200	255		
	R70	Ra		70	-		
		Ra		80	-		
Color Rendering Index	R8000	R ₉	I _F =700mA	>0	-	-	
	20050	Ra		90	-		
	R9050	R ₉		50	=		

Color Ranks(I_F=700mA)

The color ranks have chromaticity ranges within 3-step MacAdam ellipse.

		Rank	Rank	Rank	Rank	Rank	Rank
		sm223	sm273	sm303	sm353	sm403	sm503
Color Temperature (Unit: K)	T_{CP}	2200	2700	3000	3500	4000	5000
	Х	0.5018	0.4578	0.4338	0.4073	0.3818	0.3447
Center Point	у	0.4153	0.4101	0.4030	0.3917	0.3797	0.3553
Minor Axis	a	0.004002	0.004056	0.004107	0.004098	0.004071	0.003555
Major Axis	b	0.007206	0.007872	0.008391	0.008796	0.009282	0.008418
Ellipse Rotation Angle	Ф	-39.89	-36.05	-36.00	-35.47	-35.95	-31.78

		Rank sm573
Color Temperature (Unit: K)	Тср	5700
	Х	0.3287
Center Point	у	0.3417
Minor Axis	а	0.003087
Major Axis	b	0.007809
Ellipse Rotation Angle	Ф	-31.56

The color ranks have chromaticity ranges within 5-step MacAdam ellipse.

		Rank sm225	Rank sm275	Rank sm305	Rank sm355	Rank sm405	Rank sm505
Color Temperature (Unit: K)	T _{CP}	2200	2700	3000	3500	4000	5000
	Х	0.5018	0.4578	0.4338	0.4073	0.3818	0.3447
Center Point	У	0.4153	0.4101	0.4030	0.3917	0.3797	0.3553
Minor Axis	а	0.006670	0.006760	0.006845	0.006830	0.006785	0.005925
Major Axis	b	0.012010	0.013120	0.013985	0.014660	0.015470	0.014030
Ellipse Rotation Angle	Ф	-39.89	-36.05	-36.00	-35.47	-35.95	-31.78

		Rank sm575
Color Temperature (Unit: K)	Тср	5700
	Х	0.3287
Center Point	у	0.3417
Minor Axis	a	0.005145
Major Axis	b	0.013015
Ellipse Rotation Angle	Ф	-31.56

* Ranking at $T_{\rm J}{=}25^{\rm o}C$ and measured in pulse mode.

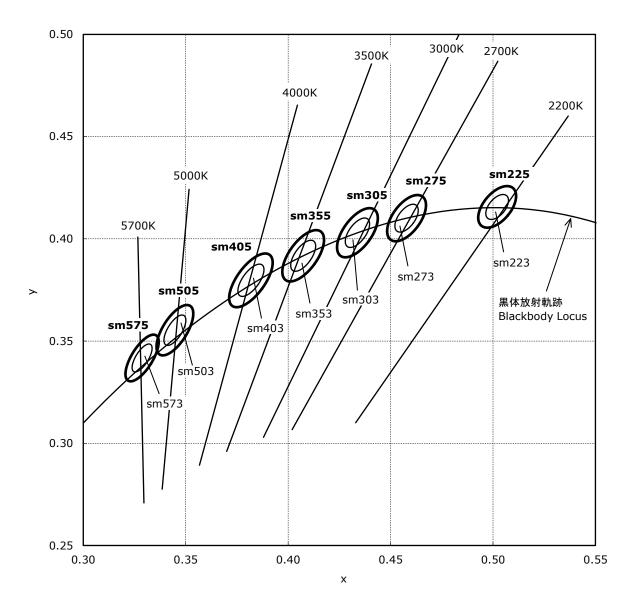
* Forward Voltage Tolerance: ±0.05V * Luminous Flux Tolerance: ±7%

* Color Rendering Index R_a Tolerance: ±2 * Color Rendering Index R₉ Tolerance: ±6.5 * Chromaticity Coordinate Tolerance: ±0.005

 st LEDs from the above ranks will be shipped. The rank combination ratio per shipment will be decided by Nichia.

Luminous Flux Ranks by Color Rank, Color Rendering Index Rank

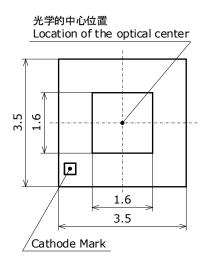
Color Coordinates	Color Rendering Index	Luminous Flux
sm223,sm225	R8000	T225f11
272 275	R8000	T250f13
sm273,sm275	R9050	T200f11
	R70	T280f14
sm303,sm305	R8000	T250f13
	R9050	T215f11
252 255	R8000	T270f13
sm353,sm355	R9050	T220f11
	R70	T295f15
sm403,sm405,sm503,sm505	R8000	T270f13
	R9050	T230f12
sm573,sm575	R9050	T230f12

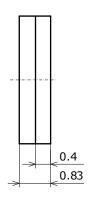


OUTLINE DIMENSIONS

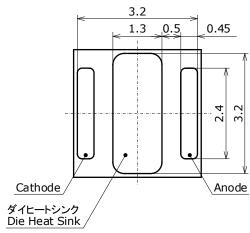
* 本製品はRoHS指令に適合しております。 This product complies with RoHS Directive. Part No. NVSW219C-V2 No. STS-DA7-19551

(単位 Unit: mm, 公差 Tolerance: ±0.2)



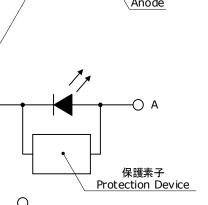






K ()

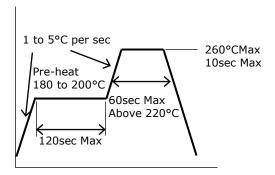
ダイヒートシンク Die Heat Sink



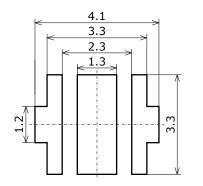
項目 Item	内容 Description
パッケージ材質 Package Materials	セラミックス Ceramics
蛍光体板材質 Phosphor sheet Materials	硬質ガラス+シリコ―ン樹脂(蛍光体入り) Hard Glass and Silicone Resin(with phosphor)
封止樹脂材質 Encapsulating Resin Materials	シリコーン樹脂(拡散剤入り) Silicone Resin(with diffuser)
電極材質 Electrodes Materials	金メッキ Au-plated
ダイヒートシンク材質 Die Heat Sink Materials	金メッキ Au-plated
質量 Weight	0.027g(TYP)

SOLDERING

• Recommended Reflow Soldering Condition(Lead-free Solder)



• Recommended Soldering Pad Pattern



(単位 Unit: mm)

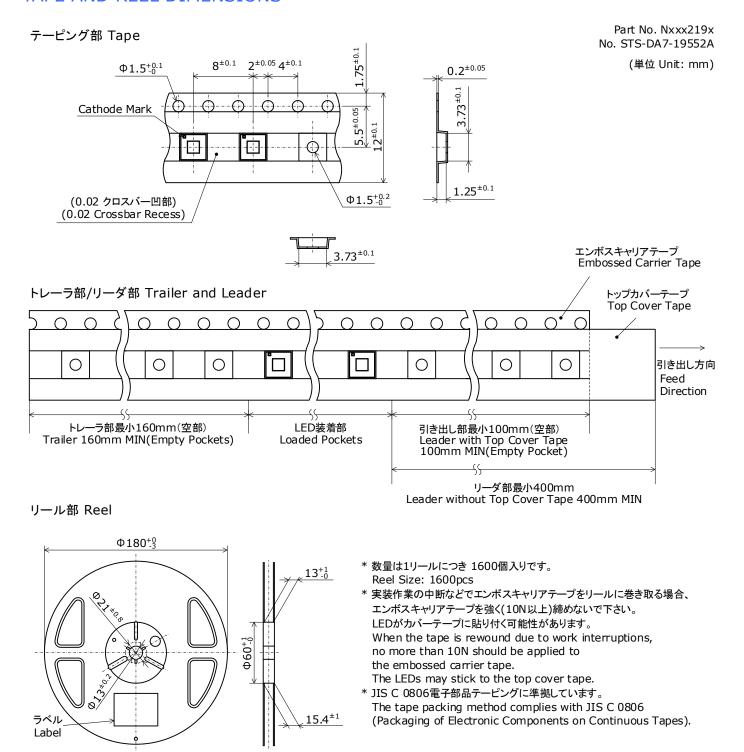
- * This LED is designed to be reflow soldered to a PCB. If dip soldered or hand soldered, Nichia will not guarantee its reliability.
- * Reflow soldering must not be performed more than twice.
- * When cooling the LEDs from the peak temperature a gradual cooling slope is recommended; do not cool the LEDs rapidly.
- * During reflow soldering, the heat and atmosphere in the reflow oven may cause the optical characteristics to degrade. In particular, reflow soldering performed with an air atmosphere may have a greater negative effect on the optical characteristics than if a nitrogen atmosphere is used; Nichia recommends using a nitrogen reflow atmosphere.
- * This LED uses a silicone resin for the encapsulating resin; the silicone resin is soft. If pressure is applied to the silicone resin, it may cause the resin to be damaged, chipped, delaminated and/or deformed. If the resin is damaged, chipped, delaminated and/or deformed, it may cause the internal connection to fail causing a catastrophic failure (i.e. the LED not to illuminate) and/or reliability issues (e.g. the LED to corrode and/or to become dimmer, the color/directivity to change, etc.). Ensure that pressure is not applied to the encapsulating resin.

If an automatic pick-and-place machine is used for the LEDs, use a pick-up nozzle that does not affect the encapsulating resin. Recommended conditions:

Nozzle contact area: The center of the phosphor sheet.

- * Once the LEDs have been soldered to a PCB, it should not be repaired/reworked. If it must be done, using a hot plate is strongly recommended. Sufficient verification should be performed prior to use to ensure that the repair/rework does not cause the LED characteristics to deteriorate.
- * The Die Heat Sink should be soldered to customer PCB. If it is difficult or impossible, use high heat-dissipating adhesive.
- * When soldering, do not apply stress to the LED while the LED is hot.
- * The soldering pad pattern above is a general recommendation for LEDs to be mounted without issues; if a high degree of precision is required for the chosen application (i.e. high-density mounting), ensure that the soldering pad pattern is optimized.
- * When flux is used, it should be a halogen free flux. Ensure that the manufacturing process is not designed in a manner where the flux will come in contact with the LEDs.
- * Ensure that there are no issues with the type and amount of solder that is being used.
- * This LED has all the electrodes on the backside; solder connections will not be able to be seen nor confirmed by a normal visual inspection. Ensure that sufficient verification is performed on the soldering conditions prior to use to ensure that there are no issues.

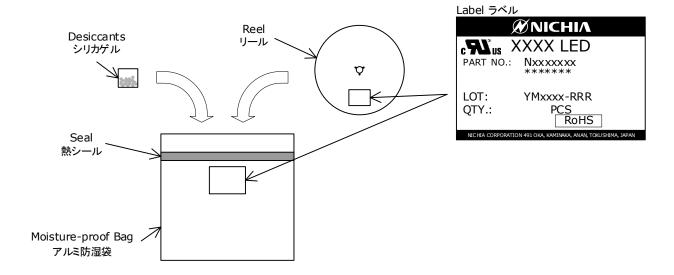
TAPE AND REEL DIMENSIONS



PACKAGING - TAPE & REEL

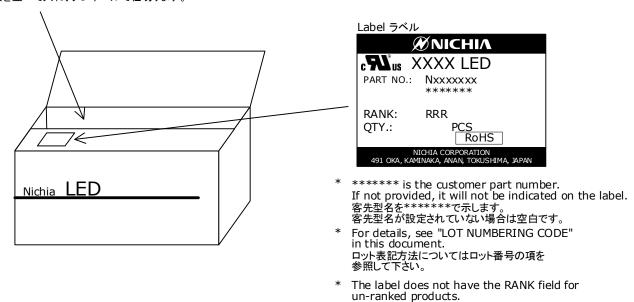
Reels are shipped with desiccants in heat-sealed moisture-proof bags. シリカゲルとともにリールをアルミ防湿袋に入れ、熱シールにより封をします。

Part No. Nxxxxxxx No. STS-DA7-4989C



Moisture-proof bags are packed in cardboard boxes with corrugated partitions.

アルミ防湿袋を並べて入れ、ダンボールで仕切ります。



ランク分けがない場合はランク表記はありません。

- * Products shipped on tape and reel are packed in a moisture-proof bag.
 They are shipped in cardboard boxes to protect them from external forces during transportation.
 本製品はテーピングしたのち、輸送の衝撃から保護するためダンボールで梱包します。
- * Do not drop or expose the box to external forces as it may damage the products. 取り扱いに際して、落下させたり、強い衝撃を与えたりしますと、製品を損傷させる原因になりますので注意して下さい。
- * Do not expose to water. The box is not water-resistant. ダンボールには防水加工がされておりませんので、梱包箱が水に濡れないよう注意して下さい。
- * Using the original package material or equivalent in transit is recommended. 輸送、運搬に際して弊社よりの梱包状態あるいは同等の梱包を行って下さい。

LOT NUMBERING CODE

Lot Number is presented by using the following alphanumeric code.

YMxxxx - RRR

Y - Year

Year	Y
2023	N
2024	0
2025	Р
2026	Q
2027	R
2028	S

Thereafter, a letter of the alphabet is assigned to each year in alphabetical order.

M - Month

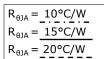
Month	М	Month	М
1	1	7	7
2	2	8	8
3	3	9	9
4	4	10	А
5	5	11	В
6	6	12	С

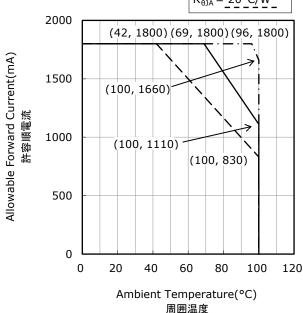
xxxx-Nichia's Product Number

RRR-Ranking by Color Coordinates, Ranking by Luminous Flux, Ranking by Color Rendering Index

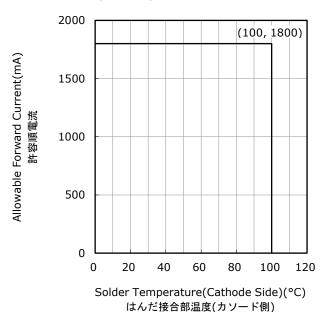
Part No. NVSW219x No. STS-DA7-19067A

Ambient Temperature vs Allowable Forward Current 周囲温度-許容順電流特性

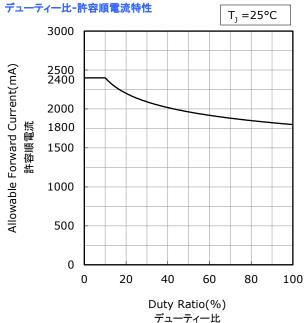




Solder Temperature(Cathode Side) vs Allowable Forward Current はんだ接合部温度(カソード側)-許容順電流特性



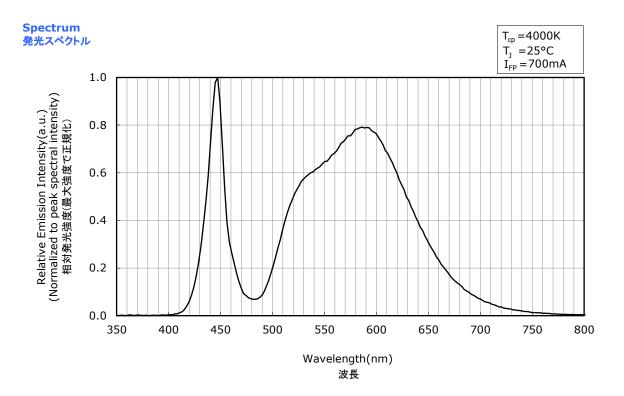
Duty Ratio vs Allowable Forward Current



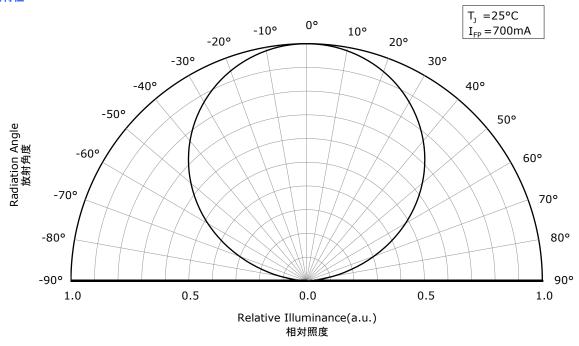
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-19553

* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



Directivity 指向特性

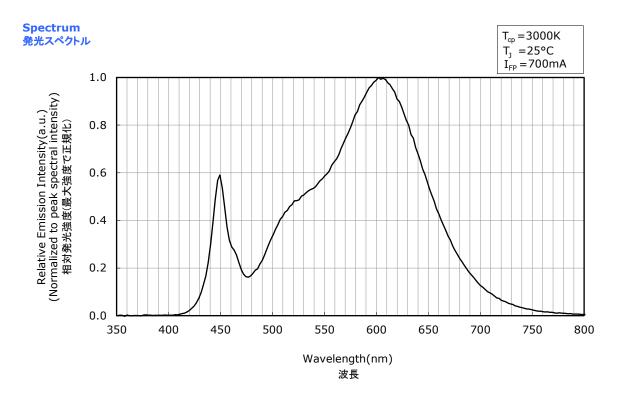


^{*} The graphs above show the characteristics for R70 LEDs of this product. 本特性は演色性ランクR70に対応しています。

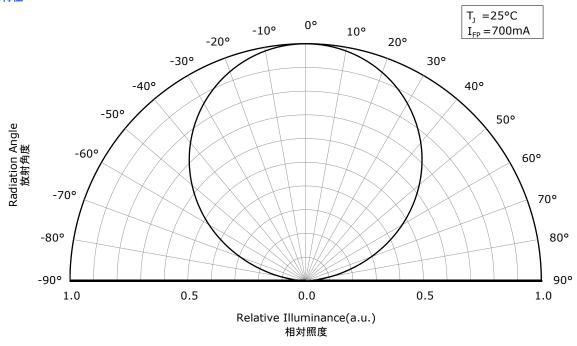
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-19554

* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



Directivity 指向特性

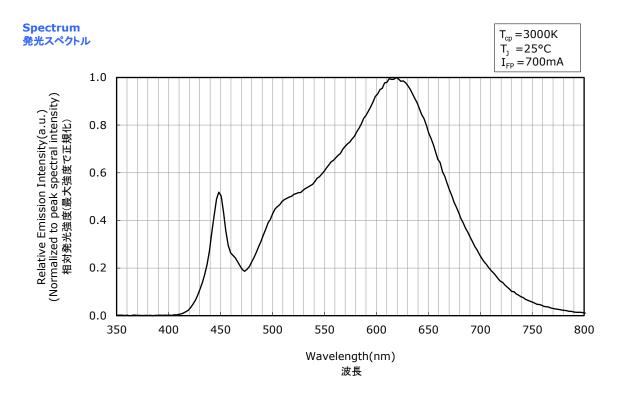


* The graphs above show the characteristics for R8000 LEDs of this product. 本特性は演色性ランクR8000に対応しています。

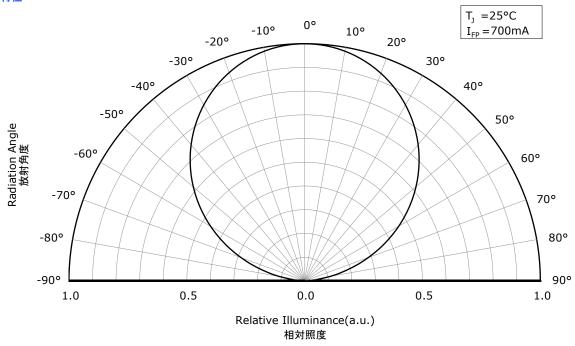
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-20440

* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



Directivity 指向特性

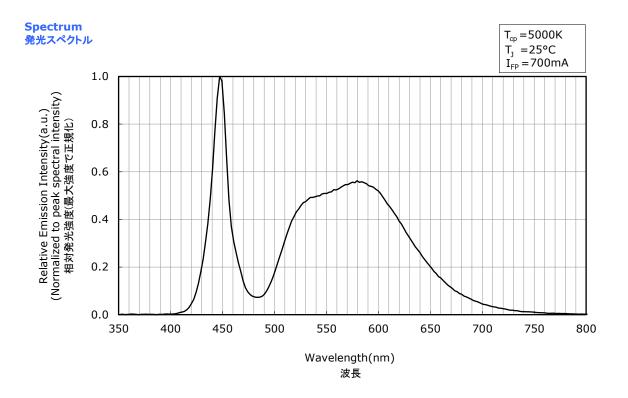


* The graphs above show the characteristics for R9050 LEDs of this product. 本特性は演色性ランクR9050に対応しています。

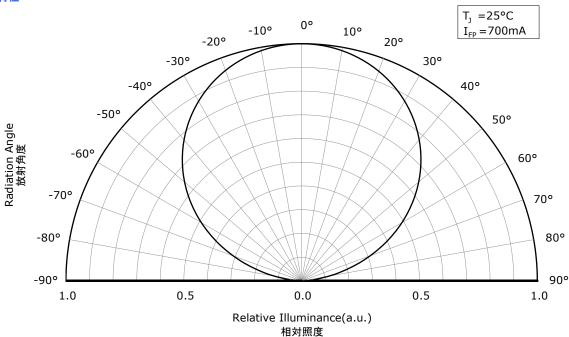
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-19555

* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



Directivity 指向特性

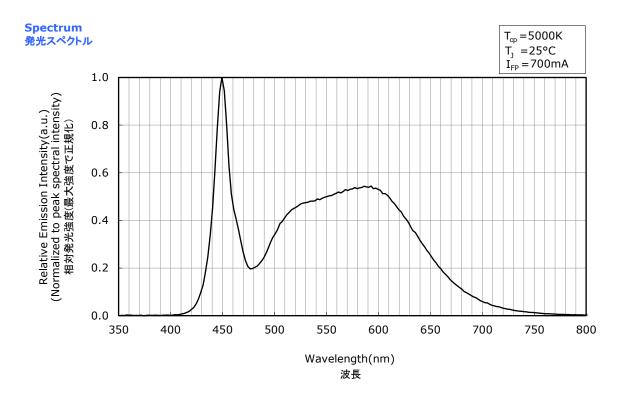


* The graphs above show the characteristics for R70 LEDs of this product. 本特性は演色性ランクR70に対応しています。

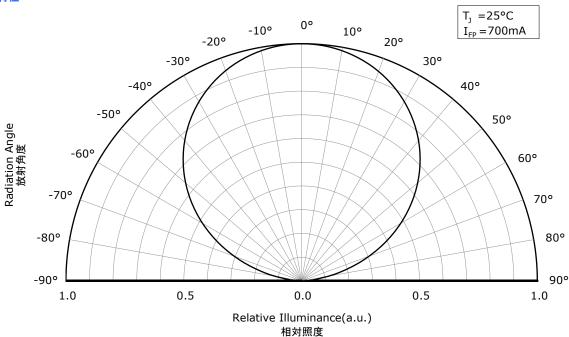
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-19556

* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



Directivity 指向特性

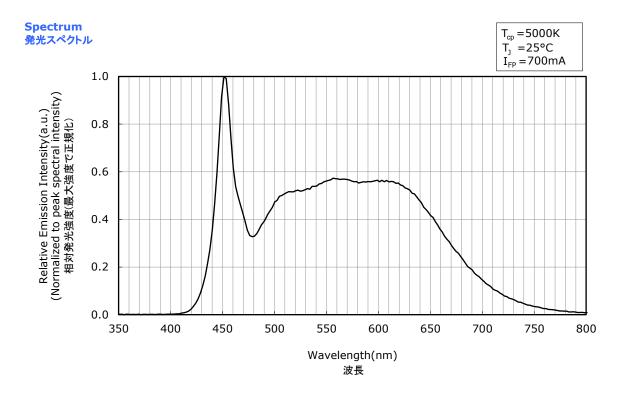


* The graphs above show the characteristics for R8000 LEDs of this product. 本特性は演色性ランクR8000に対応しています。

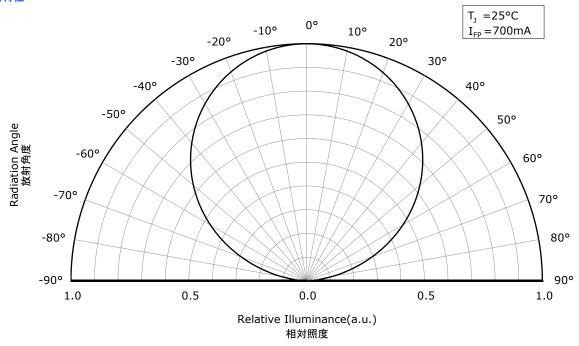
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-20441

* The following graphs show the characteristics measured in pulse mode. パルス駆動により測定しています。



Directivity 指向特性

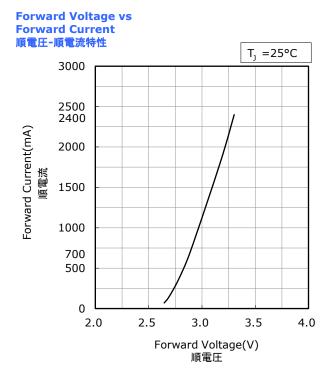


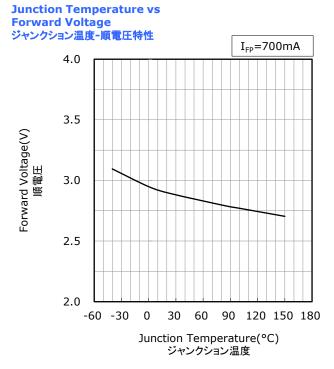
^{*} The graphs above show the characteristics for R9050 LEDs of this product. 本特性は演色性ランクR9050に対応しています。

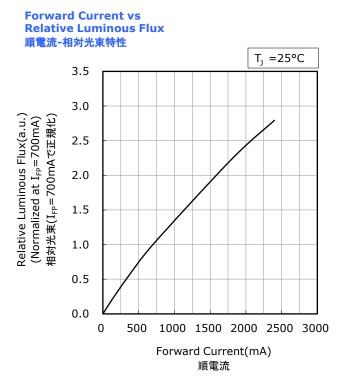
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

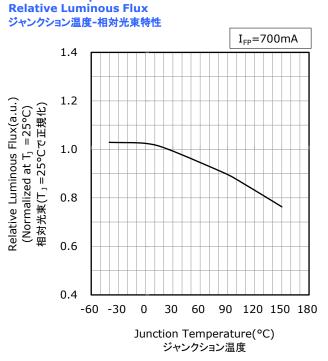
Part No. NVSW219C-V2 No. STS-DA7-19557

The following graphs show the characteristics measured in pulse mode.
 パルス駆動により測定しています。







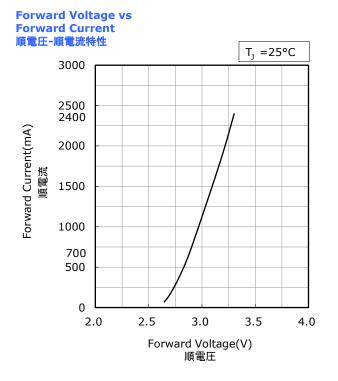


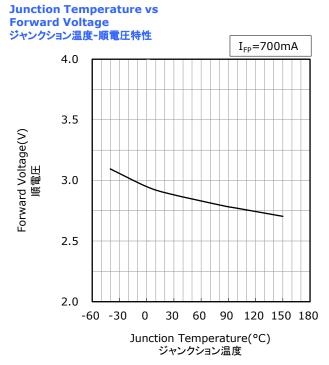
^{*} The graphs above show the characteristics for 3000K~4000K, R70 LEDs of this product. 本特性は色温度3000K~4000K、演色性ランクR70に対応しています。

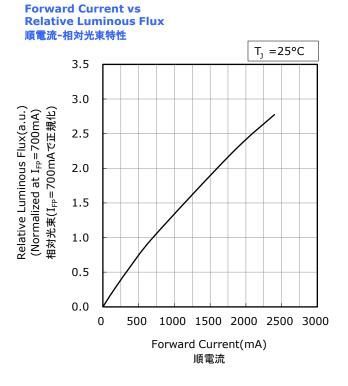
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

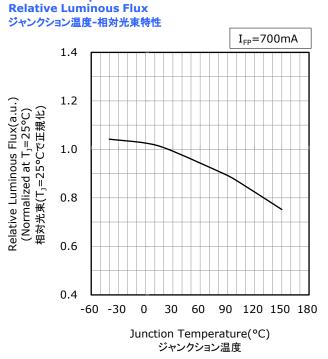
Part No. NVSW219C-V2 No. STS-DA7-19558B

The following graphs show the characteristics measured in pulse mode.
 パルス駆動により測定しています。







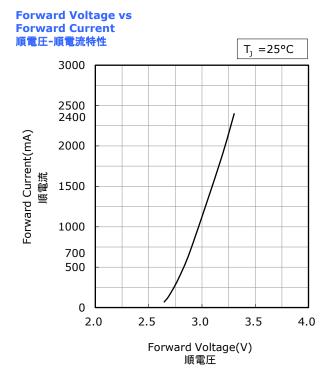


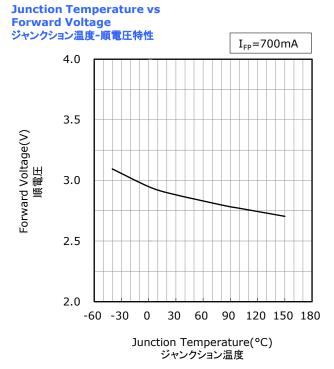
^{*} The graphs above show the characteristics for 2200K~4000K, R8000 LEDs of this product. 本特性は色温度2200K~4000K、演色性ランクR8000に対応しています。

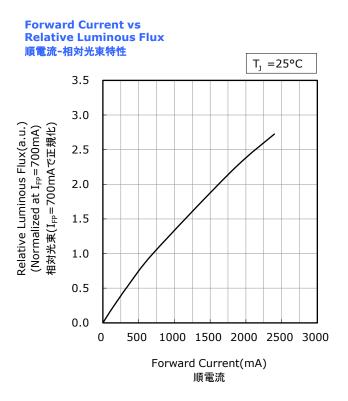
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

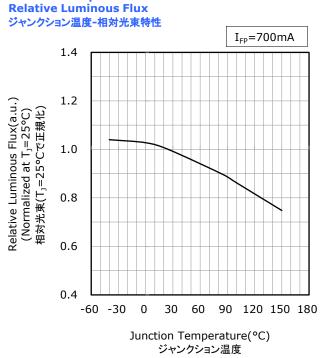
Part No. NVSW219C-V2 No. STS-DA7-20442

The following graphs show the characteristics measured in pulse mode.
 パルス駆動により測定しています。







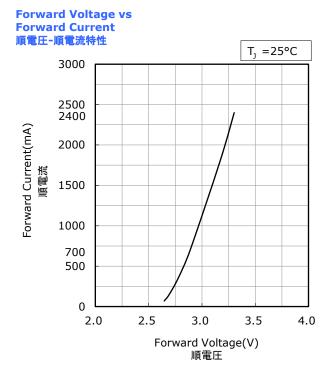


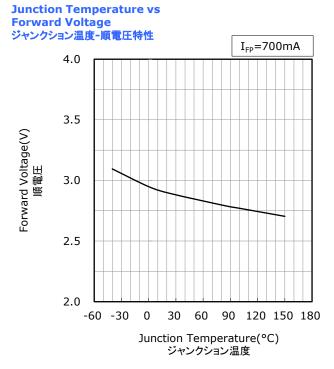
^{*} The graphs above show the characteristics for 2700K~4000K, R9050 LEDs of this product. 本特性は色温度2700K~4000K、演色性ランクR9050に対応しています。

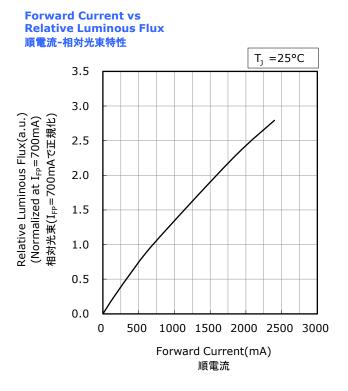
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

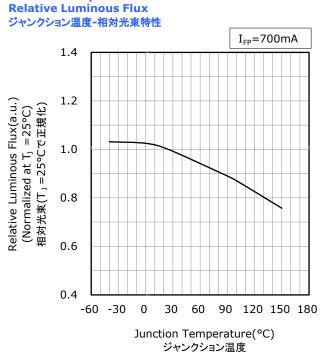
Part No. NVSW219C-V2 No. STS-DA7-19559

The following graphs show the characteristics measured in pulse mode.
 パルス駆動により測定しています。







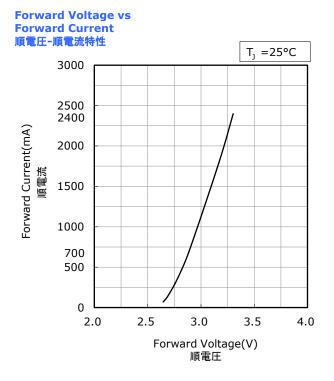


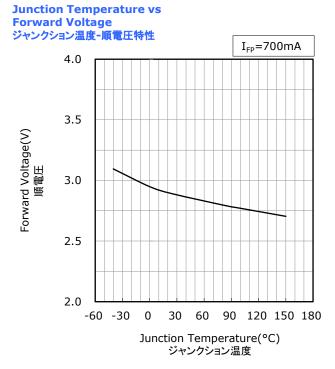
^{*} The graphs above show the characteristics for sm50x, R70 LEDs, including sub-bins, of this product. 本特性は色度ランクsm50x(ランク座標範囲内の特別ランクを含む)、演色性ランクR70に対応しています。

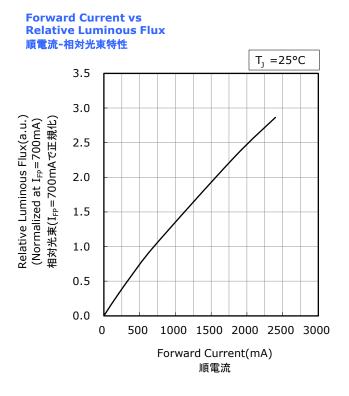
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

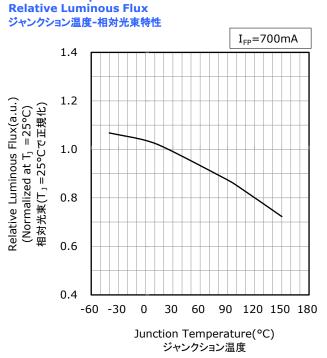
Part No. NVSW219C-V2 No. STS-DA7-19560

The following graphs show the characteristics measured in pulse mode.
 パルス駆動により測定しています。





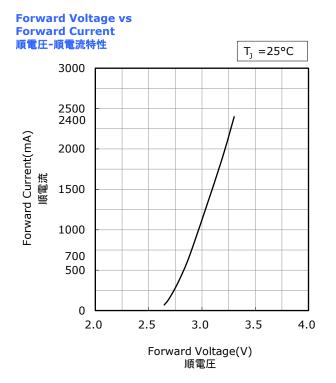


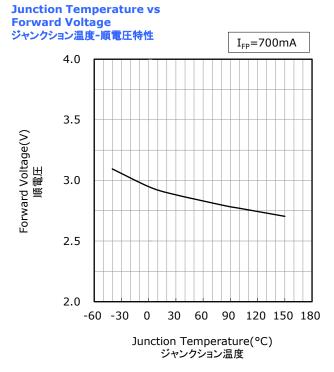


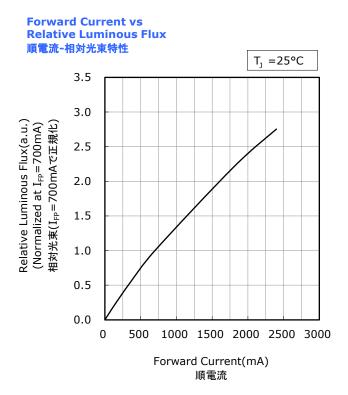
^{*} The graphs above show the characteristics for sm50x, R8000 LEDs, including sub-bins, of this product. 本特性は色度ランクsm50x(ランク座標範囲内の特別ランクを含む)、演色性ランクR8000に対応しています。

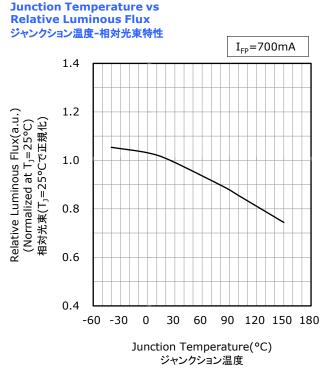
* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-20443





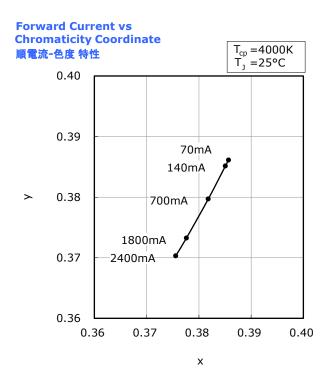


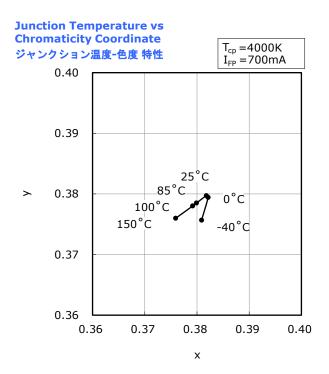


^{*} The graphs above show the characteristics for 5000K~5700K, R9050 LEDs of this product. 本特性は色温度5000K~5700K、演色性ランクR9050に対応しています。

* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-19561

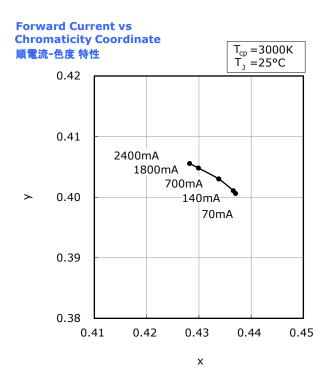


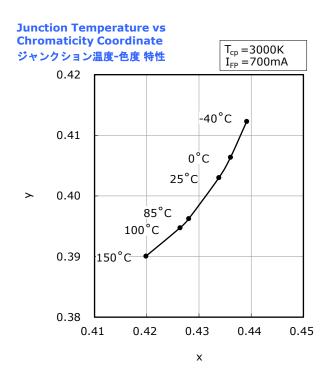


^{*} The graphs above show the characteristics for R70 LEDs of this product. 本特性は演色性ランクR70に対応しています。

* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-19562

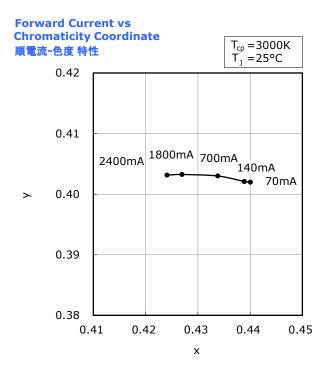


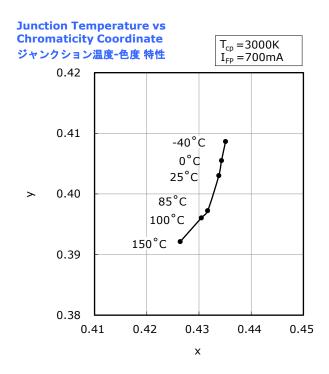


^{*} The graphs above show the characteristics for R8000 LEDs of this product. 本特性は演色性ランクR8000に対応しています。

* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-20444

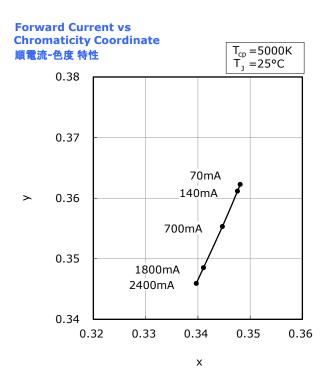


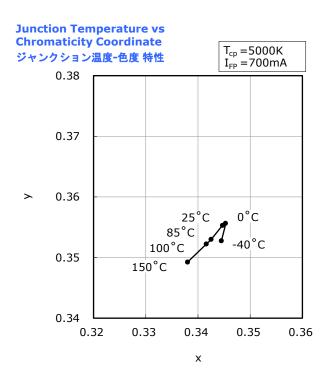


^{*} The graphs above show the characteristics for R9050 LEDs of this product. 本特性は演色性ランクR9050に対応しています。

* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-19563A

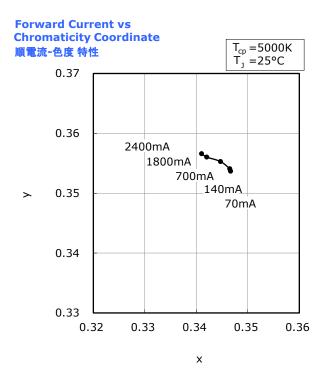


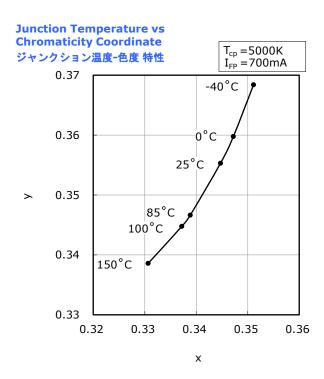


^{*} The graphs above show the characteristics for R70 LEDs of this product. 本特性は演色性ランクR70に対応しています。

* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-19564

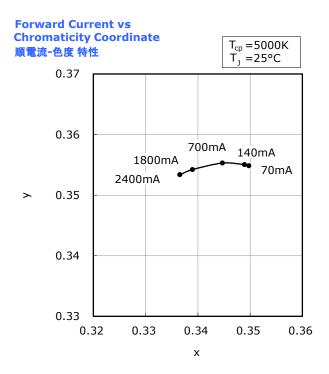


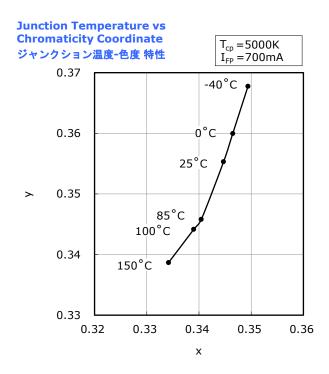


^{*} The graphs above show the characteristics for R8000 LEDs of this product. 本特性は演色性ランクR8000に対応しています。

* All characteristics shown are for reference only and are not guaranteed. 本特性は参考です。

Part No. NVSW219C-V2 No. STS-DA7-20445





^{*} The graphs above show the characteristics for R9050 LEDs of this product. 本特性は演色性ランクR9050に対応しています。

RELIABILITY

(1) Tests and Results

Test	Reference Standard	Test Conditions	Test Duration	Failure Criteria #	Units Failed/Tested
Resistance to Soldering Heat (Reflow Soldering)	JEITA ED-4701 300 301	T _{sld} =260°C, 10sec, 2reflows, Precondition: 30°C, 70%RH, 168hr		#1	0/22
Solderability	JEITA ED-4701 303 303A	T _{sld} =245±5°C, 5sec, Lead-free Solder(Sn-3.0Ag-0.5Cu)		#2	0/22
Thermal Shock(Air to Air)		-40°C to 100°C, 15min dwell	100cycles	#1	0/22
Moisture Resistance (Cyclic)	JEITA ED-4701 200 203	25°C~65°C~-10°C, 90%RH, 24hr per cycle		#1	0/22
High Temperature Storage	JEITA ED-4701 200 201	T _A =100°C	1000hours	#1	0/22
Temperature Humidity Storage	JEITA ED-4701 100 103	T _A =60°C, RH=90%	1000hours	#1	0/22
Low Temperature Storage	JEITA ED-4701 200 202	T _A =-40°C	1000hours	#1	0/22
Room Temperature Operating Life		T _A =25°C, I _F =1800mA Test board: See NOTES below	1000hours		0/22
High Temperature Operating Life		T_A =100°C, I_F =900mA Test board: See NOTES below	I 1000hours		0/22
Temperature Humidity Operating Life		60°C, RH=90%, I _F =1500mA Test board: See NOTES below		#1	0/22
Low Temperature Operating Life		T _A =-40°C, I _F =700mA Test board: See NOTES below		#1	0/22
Electrostatic Discharges	ANSI/ESDA/ JEDEC JS-001	HBM, 8kV, $1.5k\Omega$, $100pF$, $1pulse$, alternately positive or negative		#1	0/22

NOTES:

- 1) Test board: Al board thickness=1.5mm, copper layer thickness=0.105mm, R_{θJA}≈15°C/W
- 2) Measurements are performed after allowing the LEDs to return to room temperature.

(2) Failure Criteria

/					
Criteria #	Items	Conditions	Failure Criteria		
#1	Forward Voltage(V _F)	I _F =700mA	>Initial value×1.1		
	Luminous Flux(Φ _ν)	I _F =700mA	<initial td="" value×0.7<=""></initial>		
#2	Solderability	-	Less than 95% solder coverage		

CAUTIONS

(1) Storage

Conditions		Temperature	Humidity	Time
	Before Opening Aluminum Bag	≤30°C	≤90%RH	Within 1 Year from Delivery Date
Storage	After Opening Aluminum Bag	≤30°C	≤70%RH	≤168hours
Baking		65±5°C	-	≥24hours

- The storage/packaging requirements for this LED are comparable to JEDEC Moisture Sensitivity Level (MSL) 3 or equivalent. Nichia used IPC/JEDEC STD-020 as a reference to rate the MSL of this LED.
- This LED uses a package that could absorb moisture; if the package absorbs moisture and is exposed to heat during soldering, it may cause the moisture to vaporize and the package to expand and the resulting pressure may cause internal delamination. This may cause the optical characteristics to degrade. To minimize moisture absorption in storage/transit, moisture-proof aluminum bags are used for the LEDs with a silica gel packet to absorb any air moisture in the bag. The silica gel beads turn blue to red as they absorb moisture.
- Once the moisture-proof aluminum bag is open, ensure that the LED is soldered to a PCB within the range of the conditions above. To store any remaining unused LEDs, use a hermetically sealed container with silica gel desiccants. Nichia recommends placing them back to the original moisture-proof bag and reseal it.
- If the "After Opening" storage time has been exceeded or any pink silica gel beads are found, ensure that the LED are baked before use. Baking should only be done once.
- The parts/materials (e.g. housing, gasket/seal, secondary lens, lens cover, thermal grease, etc.) used with the LED in the same assembly/system may release corrosive gases containing sulfur, halogens, etc. A light-up test, sufficient verifications, etc. must be performed at the finished product level (i.e. automotive headlamp, luminaire, etc.) prior to use taking into consideration the conditions/environments in which the finished product will actually be used to ensure that the expected performance for the finished product is maintained. See below for the detailed information.

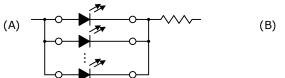
Issues that may be caused by corrosive gases containing sulfur, halogens, etc.:

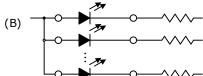
This LED has plated parts. If the LED is exposed to corrosive gases containing sulfur, halogens, etc., it may cause the plated surface to tarnish. If the gases penetrate the LED (e.g. emitting surface, package material, etc.), it may cause the surface of the plated parts inside the package to tarnish. In addition, it has been confirmed that if a silicone resin is used in the LED, the gases may accelerate degradation of the silicone resin. As a result, the optical characteristics may be adversely affected (i.e. significant reduction in the brightness, significant color shift, etc.); in the worst case, the circuit could become open causing a catastrophic failure (i.e. the LED not to illuminate). When determining the storage environment for the LED and/or selecting parts/materials that will be used with the LED in the finished product, it must be ensured prior to use that corrosive gases containing sulfur, halogens, etc. are not generated.

- To avoid condensation, the LEDs must not be stored in areas where temperature and humidity fluctuate greatly.
- Do not store the LEDs in a dusty environment.
- Do not expose the LEDs to direct sunlight and/or an environment over a long period of time where the temperature is higher than normal room temperature.

(2) Directions for Use

• The circuit must be designed to ensure that the Absolute Maximum Ratings are not exceeded for each LED. The LEDs should be operated at a constant current per LED. In the case of operating at a constant voltage, Circuit B is recommended. If Circuit A is used, it may cause the currents flowing through the LEDs to vary due to the variation in the forward voltage characteristics of the LEDs on the circuit.





- This LED is designed to be operated at a forward current. Ensure that no voltage is applied to the LED in the forward/reverse direction while the LED is off. If the LEDs are used in an environment where reverse voltages are applied to the LED continuously, it may cause electrochemical migration to occur causing the LED to be damaged. When not in use for a long period of time, the system's power should be turned off to ensure that there are no issues/damage.
- To stabilize the LED characteristics while in use, Nichia recommends that the LEDs are operated at currents ≥ 10% of the sorting current.
- Ensure that transient excessive voltages (e.g. lightning surge) are not applied to the LEDs.
- If the LEDs are used for outdoor applications, ensure that necessary measures are taken (e.g. protecting the LEDs from water/salt damage and high humidity).

(3) Handling Precautions

- Do not handle the LEDs with bare hands as it will contaminate the LED surface and may affect the optical characteristics: it might cause the LED to be deformed and/or the bump to break, which will cause the LED not to illuminate.
- Ensure that when handling the LEDs with tweezers, excessive force is not applied to the LED. Otherwise, it may cause damage to the resin (e.g. cut, scratch, chip, crack, delamination and deformation) and the internal connection to fail causing a catastrophic failure (i.e. the LED not to illuminate).
- Dropping may cause damage to the LED (e.g. deformation).
- Do not stack assembled PCBs together. Otherwise, it may cause damage to the resin (e.g. cut, scratch, chip, crack, delamination and deformation) and the internal connection to fail causing a catastrophic failure (i.e. the LED not to illuminate).

(4) Design Consideration

- If the LEDs are soldered to a PCB and the PCB assembly is bent (e.g. PCB depanding process), it may cause the LED package to break. The PCB layout should be designed to minimize the mechanical stress on the LEDs when the PCB assembly is bent/warped.
- The amount of mechanical stress exerted on the LED from depaneling may vary depending on the LED position/orientation on the PCB assembly (e.g. especially in areas near V-groove scores). The PCB layout should be designed to minimize the mechanical stress on the LEDs when the PCB is separated into individual PCB assemblies.
- To separate a PCB populated with the LEDs, use a specially designed tool. Do not break the PCB by hand.
- If an aluminum-core PCB is used to operate the LEDs, it may cause thermal stress during operation causing damage to the solder joints (e.g. crack). Ensure that sufficient verification is performed prior to use.
- The parts/materials (e.g. housing, gasket/seal, secondary lens, lens cover, thermal grease, etc.) used with the LED in the same assembly/system may release corrosive gases containing sulfur, halogens, etc., and/or volatile organic compounds (VOCs). A light-up test, sufficient verifications, etc. must be performed at the finished product level (i.e. automotive headlamp, luminaire, etc.) prior to use taking into consideration the conditions/environments in which the finished product will actually be used to ensure that the expected performance for the finished product is maintained. See below for the detailed information.

Issues that may be caused by corrosive gases containing sulfur, halogens, etc.:

This LED has plated parts. If the LED is exposed to corrosive gases containing sulfur, halogens, etc., it may cause the plated surface to tarnish. If the gases penetrate the LED (e.g. emitting surface, package material, etc.), it may cause the surface of the plated parts inside the package to tarnish. In addition, it has been confirmed that if a silicone resin is used in the LED, the gases may accelerate degradation of the silicone resin. As a result, the optical characteristics may be adversely affected (i.e. significant reduction in the brightness, significant color shift, etc.); in the worst case, the circuit could become open causing a catastrophic failure (i.e. the LED not to illuminate). When determining the storage environment for the LED and/or selecting parts/materials that will be used with the LED in the finished product, it must be ensured prior to use that corrosive gases containing sulfur, halogens, etc. are not generated.

Issues that may be caused by VOCs:

If VOCs that have been released from the parts/materials and/or organic additives used with the LED in the finished product penetrate into the LED and remain inside the LED, the VOCs can discolor after being exposed to heat and/or photon energy. This may cause the optical characteristics to be adversely affected (i.e. significant reduction in the brightness, significant color shift, etc.). This adverse effect may be improved by ventilating the environment (i.e. the LED is not used in a hermetically sealed environment) to prevent the VOCs from remaining inside the LED. When selecting parts/materials that will be used with the LED in the finished product, it must be ensured prior to use that there are no issues with the substances found in those parts/materials and/or that the expected performance for the finished product is maintained by performing a light-up test, sufficient verifications etc. taking into consideration the conditions/environments in which the finished product will actually be used.

• The characteristics of the LEDs (e.g. chromaticity, color rendering index, etc.) will vary depending on how the LEDs are designed into the application (e.g. secondary lens, luminaire cover/housing, etc. for ease of dissipation), how they were assembled, under what conditions/environments they are used (e.g. operating current/temperature, etc.), and how long they have been used (e.g. storage/operating hours, etc.). To ensure that there are no issues (e.g. deviations/changes in the characteristics, etc.) with the chosen application, perform a sufficient verification prior to use.

(5) Electrostatic Discharge (ESD)

- This LED is sensitive to transient excessive voltages (e.g. ESD, lightning surge). If this excessive voltage occurs in the circuit, it may cause the LED to be damaged causing issues (e.g. the LED to become dimmer or not to illuminate [i.e. catastrophic failure]). Ensure that when handling the LEDs, necessary measures are taken to protect them from an ESD discharge. The following examples are recommended measures to eliminate the charge:
 - Grounded wrist strap, ESD footwear, clothes, and floors
 - Grounded workstation equipment and tools
 - ESD table/shelf mat made of conductive materials
- Ensure that all necessary measures are taken to prevent the LEDs from being exposed to transient excessive voltages (e.g. ESD, lightning surge):
 - tools, jigs, and machines that are used are properly grounded
 - appropriate ESD materials/equipment are used in the work area
 - the system/assembly is designed to provide ESD protection for the LEDs
- If the tool/equipment used is an insulator (e.g. glass cover, plastic, etc.), ensure that necessary measures have been taken to protect the LED from transient excessive voltages (e.g. ESD). The following examples are recommended measures to eliminate the charge:
 - Dissipating static charge with conductive materials
 - Preventing charge generation with moisture
 - Neutralizing the charge with ionizers
- To detect if an LED was damaged by transient excess voltages (i.e. an ESD event during the system's assembly process), perform
 a characteristics inspection (e.g. forward voltage measurement, light-up test) at low current (≤1mA).
- Failure Criteria: V_F<2.0V at I_F=0.5mA

If the LED is damaged by transient excess voltages (e.g. ESD), it will cause:

- the Forward Voltage (V_F) to decrease
- the LED not to illuminate at a low current

(6) Thermal Management

- When using the LEDs for the chosen application, it is necessary to consider the heat generated from the LEDs during operation. The increase in the temperature of an LED chip while in operation may vary depending on variations in the thermal resistance, the thermal resistance of the chosen PCB and the density of LEDs in the system/assembly. The Absolute Maximum Junction Temperature (T_J) must not be exceeded under any circumstances; ensure that heat is not concentrated in an area and is properly managed in the system/assembly.
- The operating current should be determined by considering the temperature conditions surrounding the LED (i.e. T_A). Ensure that when operating the LED, proper measures are taken to dissipate the heat.
- The following equations can be used to calculate the LED temperature (i.e. T₁) once the saturation temperature at the junction has been reached.

```
1) T_J = T_A + R_{\theta JA} \cdot W 2) T_J = T_S + R_{\theta JS} \cdot W
*T_J = LED Junction Temperature: °C
```

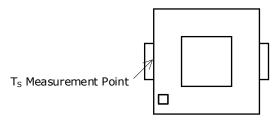
T_A=Ambient Temperature: °C

T_S=Soldering Temperature (Cathode Side): °C

R_{0JA}=Thermal Resistance from Junction to Ambient: °C/W

R_{0JS}=Thermal Resistance from Junction to T_S Measurement Point: °C/W

W=Input Power($I_F \times V_F$): W



(7) Cleaning

- Do not clean the LEDs with water, benzine and/or thinner.
- To clean the LEDs, use isopropyl alcohol (IPA). If another solvent is used, it may cause the LED package/resin to be damaged causing issues; ensure that sufficient verification is performed prior to use. Additionally, ensure that the solvent being used does not cause any other issues (e.g. CFC-based solvents are heavily regulated).
- If an LED is contaminated (e.g. dust/dirt), use a cloth soaked with isopropyl alcohol (IPA). Ensure that the cloth is firmly squeezed before wiping the LED.
- Do not clean the LEDs with an ultrasonic cleaner. If cleaning must be done, ensure that sufficient verification is performed by using a finished assembly with LEDs to determine cleaning conditions (e.g. ultrasonic power, LED position on the PCB assembly) that do not cause an issue

(8) Eye Safety

- There may be two important international specifications that should be noted for safe use of the LEDs: IEC 62471:2006

 Photobiological safety of lamps and lamp systems and IEC 60825-1:2001 (i.e. Edition 1.2) Safety of Laser Products Part 1:

 Equipment Classification and Requirements. Ensure that when using the LEDs, there are no issues with the following points:
 - LEDs have been removed from the scope of IEC 60825-1 since IEC 60825-1:2007 (i.e. Edition 2.0) was published. However, depending on the country/region, there are cases where the requirements of the IEC 60825-1:2001 specifications or equivalent must be adhered to.
 - LEDs have been included in the scope of IEC 62471:2006 since the release of the specification in 2006.
 - Most Nichia LEDs will be classified as the Exempt Group or Risk Group 1 according to IEC 62471:2006. However, in the case of high-power LEDs containing blue wavelengths in the emission spectrum, there are LEDs that will be classified as Risk Group 2 depending on the characteristics (e.g. radiation flux, emission spectrum, directivity, etc.)
 - If the LED is used in a manner that produces an increased output or with an optic to collimate the light from the LED, it may cause damage to the human eye.
- If an LED is operated in a manner that emits a flashing light, it may cause health issues (e.g. visual stimuli causing eye discomfort). The system should be designed to ensure that there are no harmful effects on the human body.

(9) Miscellaneous

- Nichia warrants that the discrete LEDs will meet the requirements/criteria as detailed in the Reliability section within this specification. If the LEDs are used under conditions/environments deviating from or inconsistent with those described in this specification, the resulting damage and/or injuries will not be covered by this warranty.
- Nichia warrants that the discrete LEDs manufactured and/or supplied by Nichia will meet the requirements/criteria as detailed in the Reliability section within this specification; it is the customer's responsibility to perform sufficient verification prior to use to ensure that the lifetime and other quality characteristics required for the intended use are met.
- The applicable warranty period is one year from the date that the LED is delivered. In the case of any incident that appears to be in breach of this warranty, the local Nichia sales representative should be notified to discuss instructions on how to proceed while ensuring that the LED in question is not disassembled or removed from the PCB if it has been attached to the PCB. If a breach of this warranty is proved, Nichia will provide the replacement for the non-conforming LED or an equivalent item at Nichia's discretion. FOREGOING ARE THE EXCLUSIVE REMEDIES AVAILABLE TO THE CUSTOMER IN RESPECT OF THE BREACH OF THE WARRANTY CONTAINED HEREIN, AND IN NO EVENT SHALL NICHIA BE RESPONSIBLE FOR ANY INDRECT, INCIDENTAL OR CONSEQUENTIAL LOSSES AND/OR EXPENSES (INCLUDING LOSS OF PROFIT) THAT MAY BE SUFFERED BY THE CUSTOMER ARISING OUT OF A BREACH OF THE WARRANTY.
- NICHIA DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE.
- This LED is intended to be used for general lighting, household appliances, electronic devices (e.g. mobile communication devices); it is not designed or manufactured for use in applications that require safety critical functions (e.g. aircraft, automobiles, combustion equipment, life support systems, nuclear reactor control system, safety devices, spacecraft, submarine repeaters, traffic control equipment, trains, vessels, etc.). If the LEDs are planned to be used for these applications, unless otherwise detailed in the specification, Nichia will neither guarantee that the LED is fit for that purpose nor be responsible for any resulting property damage, injuries and/or loss of life/health. This LED does not comply with IATF 16949 and is not intended for automotive applications.
- The customer will not reverse engineer, disassemble or otherwise attempt to extract knowledge/design information from the LED.
- All copyrights and other intellectual property rights in this specification in any form are reserved by Nichia or the right holders who have granted Nichia permission to use the content. Without prior written permission from Nichia, no part of this specification may be reproduced in any form or by any means.
- Both the customer and Nichia will agree on the official specifications for the supplied LEDs before any programs are officially launched. Without this agreement in writing (i.e. Customer Specific Specification), changes to the content of this specification may occur without notice (e.g. changes to the foregoing specifications and appearance, discontinuation of the LEDs, etc.).